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aluminum conductor an additive which suppresses the diffusion of copper, the precipitation can be prevented.

In the Claims:

Please cancel claims 5-9, 11 without prejudice.

Please amend claims 1, 2, 4 and 10 as follows:

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Sub
101

1. (Amended) A semiconductor device comprising a semiconductor substrate, and aluminum conductors formed on a side of a main face of the substrate which aluminum conductors comprise aluminum as a main constituent thereof, said aluminum conductors containing copper and nickel.

2. (Amended) A semiconductor device according to claim 1, wherein said aluminum conductors have at least one area in which conductor spacing is not more than 0.4 μm .

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4. (Amended) A semiconductor device comprising a semiconductor substrate, and aluminum conductors formed on a side of a main face of the substrate which aluminum conductors comprise aluminum as a main constituent thereof, a film adjacent to said aluminum conductors which adjacent film comprises titanium or titanium nitride as a main constituent thereof, said aluminum conductors containing copper and nickel.
